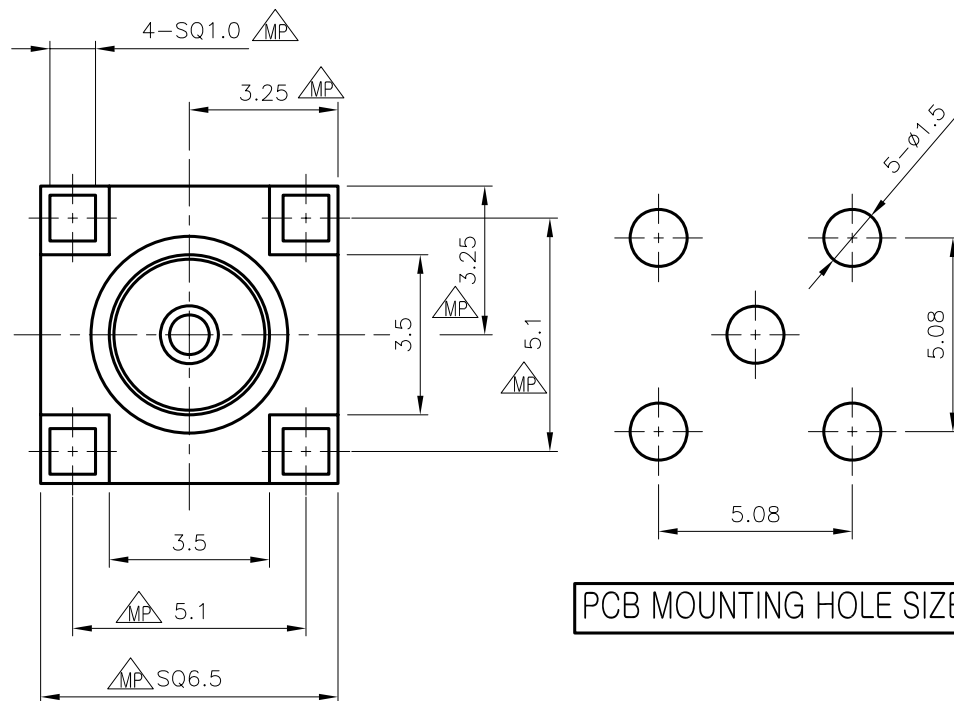
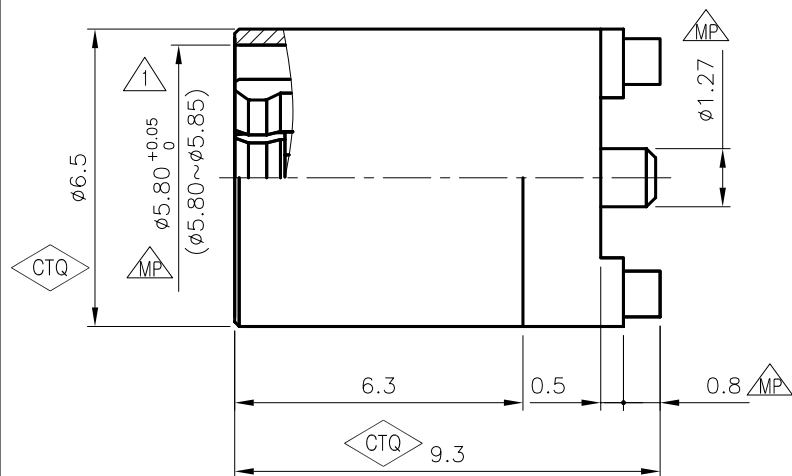


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	H.J.LEE	I.C.KIM	2015.03.18.
1	[실변No.201506-0021]내경부 관리 치수 변경(CTQ-> MP Point로 변경) ($\phi 5.85 \pm 0.1 \rightarrow \phi 5.80 + 0.05/0$)	H.J.LEE	I.C.KIM	2015.06.23.



PCB MOUNTING HOLE SIZE

NOTE

1. 도금 사양

- BODY : 하지 Ni ($2\mu m \sim 10\mu m$)
Gold ($0.06\mu m \sim 2\mu m$)
- CONTACT : 하지 Ni ($2\mu m \sim 10\mu m$)
Gold ($0.06\mu m \sim 2\mu m$)
- JACK : 하지 Ni ($2\mu m \sim 10\mu m$)
Gold ($0.06\mu m \sim 2\mu m$)

2. 기재한 관리 공차외에 치수는 일반공차 적용

4	JACK	1	MBsBD	Note 참조	DJA00159-5/6
3	INSULATOR	1	TEFLON		DIN02179-N/1
2	CONTACT	1	BeCu	Note 참조	DCT03443-5/1
1	BODY	1	MBsBD	Note 참조	DBD03910-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2015. 06. 23.			 KJ COMTECH RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017 KJ COMTECH CO.,LTD.
	Angle	APPROVED BY	I.C.KIM		
	$\pm 1^{\circ}$	CHECKED BY	S.M.LEE		
MATERIAL		DRAWN BY	H.J.LEE		TITLE SMBL50 PCB JS-4R
FINISH		SCALE	UNIT		
		6/1	mm		A4
		DWG NO. CN03313-7/5			
		REVISION 1			SHEET 1 of 1